

# ISL78235R5668

## Automotive 5A Synchronous Buck Regulator

FN8769  
Rev 2.00  
Apr 19, 2018

The [ISL78235R5668](#) is a highly efficient, monolithic, synchronous step-down DC/DC converter that can deliver 5A continuous and up to 8A pulsed output current from a 2.7V to 5.5V input supply. The device uses peak current mode control architecture to achieve very low duty cycle operation at high frequency with fast transient response and excellent loop stability.

The ISL78235R5668 integrates a low ON-resistance P-channel (35mΩ, typical) high-side FET and N-channel (11mΩ, typical) low-side FET to maximize efficiency and minimize external component count. The 100% duty cycle operation allows less than 250mV dropout voltage at 5A output current. The operating frequency of the Pulse-Width Modulator (PWM) is adjustable from 500kHz to 4MHz. The default switching frequency of 2MHz is set by connecting the FS pin high.

The ISL78235R5668 can be configured for discontinuous (PFM) or forced continuous (PWM) operation at light load. Forced continuous operation reduces noise and RF interference, while discontinuous mode provides higher efficiency by reducing switching losses at light loads.

Fault protection is provided by internal hiccup mode current limiting during short-circuit and overcurrent conditions. The device also integrates output overvoltage and over-temperature protections. A power-good monitor indicates when the output is in regulation. The ISL78235R5668 offers a 1ms Power-Good (PG) timer at power-up.

When in shutdown, the ISL78235R5668 discharges the output capacitor through an internal 100Ω soft-stop switch. Other features include internal fixed or adjustable soft-start and internal/external compensation.

The ISL78235R5668 is available in a 3mmx3mm 16 Ld Thin Quad Flat No-lead (TQFN) Pb-free package with an exposed pad for improved thermal performance. The ISL78235R5668 is rated to operate across the temperature range of -40°C to +85°C.

## Features

- 2.7 to 5.5V input voltage range
- 5A continuous; 8A pulse output current operation
- 2MHz default switching frequency
- 100ns guaranteed phase minimum on-time for wide output regulation
- Adjustable switching frequency from 500kHz to 4MHz
- External synchronization from 1MHz to 4MHz
- Optional PFM mode for light-load efficiency improvement
- Very low ON-resistance HS/LS switches: 35mΩ/11mΩ
- Internal 1ms or adjustable external soft-start
- Soft-stop output discharge during disable
- OTP, OCP, output OVP, and input UVLO protections
- 1% reference accuracy over-temperature
- Up to 95% efficiency
- [AEC-Q100](#) qualified

## Applications

- Automotive infotainment power
- DC/DC point-of-load modules
- μC/μP, FPGA, and DSP power
- Video processor/SOC power
- Li-ion battery powered devices

## Related Literature

For a full list of related documents, visit our website

- [ISL78235R5668](#) product page

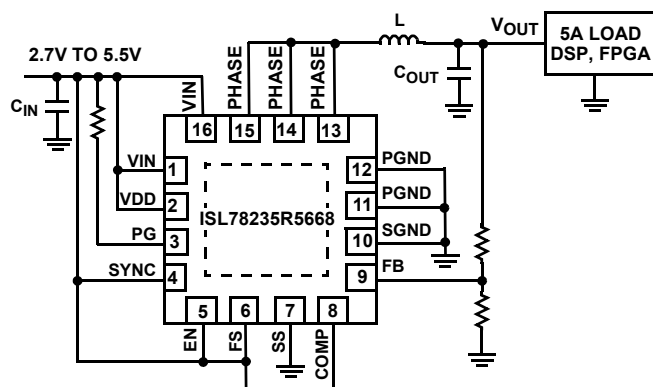


FIGURE 1. TYPICAL APPLICATION: 5A BUCK REGULATOR

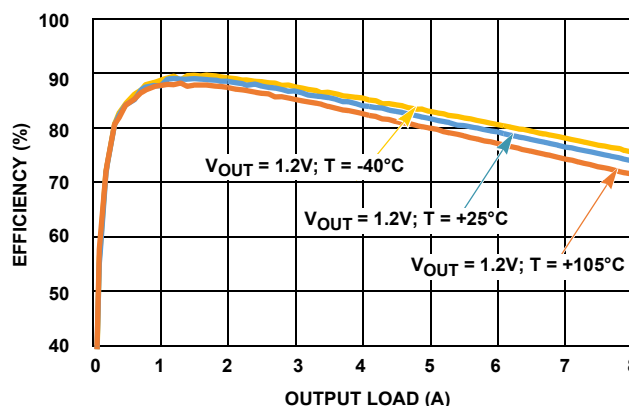


FIGURE 2. EFFICIENCY vs LOAD ( $V_{IN} = 5V$ )

## Functional Block Diagram

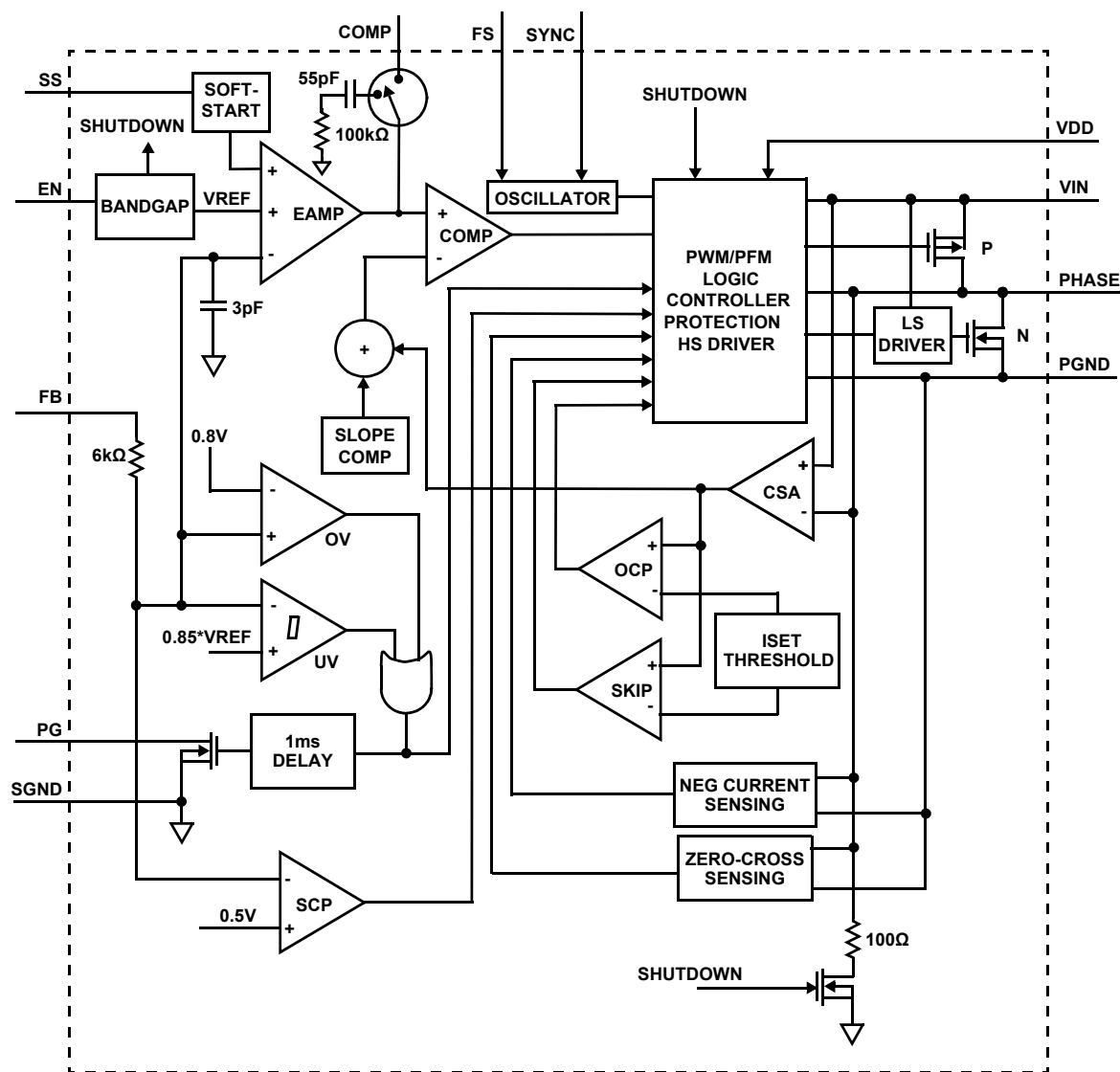
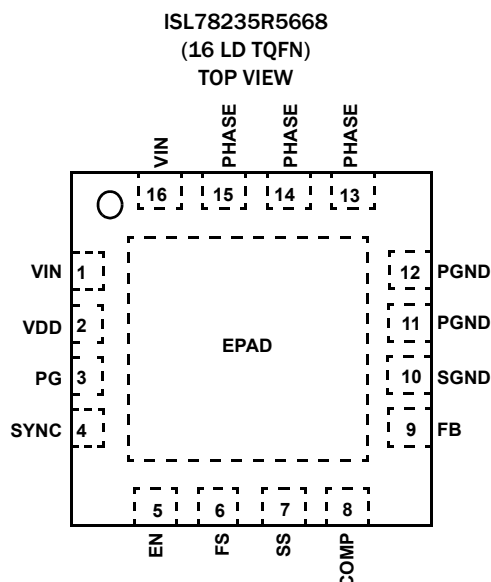


FIGURE 3. FUNCTIONAL BLOCK DIAGRAM

## Pin Configuration



## Pin Descriptions

PIN NUMBER	PIN NAME	DESCRIPTION
1, 16	VIN	Input supply voltage. Place a minimum of two 22 $\mu$ F low ESR ceramic capacitors from VIN to PGND as close as possible to the IC for decoupling.
2	VDD	Input supply voltage for the logic circuitry. A 0.1 $\mu$ F high frequency decoupling ceramic capacitor should also be placed close to the VDD and SGND pin. <b>Connect to the VIN pin.</b>
3	PG	PG is an open-drain output for power-good indication. Use a 10k $\Omega$ to 100k $\Omega$ pull-up resistor connected from PG to VIN. At power-up or EN high, PG rising edge is delayed by 1ms upon output voltage within regulation.
4	SYNC	Mode selection pin. Connect to logic high or input voltage VIN for forced PWM mode. Connect to logic low or ground for PFM mode. Connect to an external function generator for synchronization with a positive edge trigger. In external synchronization the ISL78235R5668 operates in forced PWM mode. The transition to and from the internal oscillator to external synchronization is seamless and does not require disabling of the ISL78235R5668. An internal 1M $\Omega$ pull-down resistor to SGND prevents an undefined logic state if the SYNC pin is floating.
5	EN	Regulator enable pin. The regulator is enabled when driven logic high. The regulator is shut down and the PHASE pin discharges the output capacitor when enable pin is driven low.
6	FS	The FS pin sets the internal oscillator switching frequency using a resistor, R <sub>FS</sub> , from the FS pin to GND. The frequency of operation may be programmed between 500kHz to 4MHz. The switching frequency is 2MHz if the FS is connected to VIN.
7	SS	SS is used to adjust the soft-start time. Connect the SS pin to SGND for internal 1ms soft-start time. Connect a capacitor from SS to SGND to adjust the soft-start time. Do not use more than 33nF on the SS pin.
8	COMP	The output of the error amplifier if COMP is not connected to VDD. An external compensation network must be used if COMP is not tied to VDD. If COMP is tied to VDD, the error amplifier output is internally compensated. External compensation network across COMP and SGND may be required to improve the loop compensation of the amplifier.
9	FB	The feedback network of the regulator, FB, is the negative input to the transconductance error amplifier. The output voltage is set by an external resistor divider connected to FB. With a properly selected divider, the output voltage can be set to any voltage between the power rail (reduced by converter losses) and the 0.6V reference. In addition, the regulator power-good and undervoltage protection circuitry use FB to monitor the regulator output voltage.
10	SGND	Analog signal ground. <b>Connect to PGND.</b>
11, 12	PGND	Power ground.
13, 14, 15	PHASE	Switching node connections. Connect to one terminal of the inductor. This pin is discharged by a 100 $\Omega$ resistor when the device is disabled. See <a href="#">"Functional Block Diagram" on page 2</a> for more detail.
Exposed Pad	EPAD	The exposed pad must be connected to the SGND pin for proper electrical performance. Place as many vias as possible under the pad connecting to SGND plane for optimal thermal performance.

## Ordering Information

PART NUMBER (Notes 1, 2, 3)	PART MARKING	OUTPUT VOLTAGE (V)	TEMP. RANGE (°C)	TAPE AND REEL QUANTITY (UNITS)	PACKAGE (RoHS Compliant)	PKG. DWG. #
ISL78235ARZ-TR5668	8235	Adjustable	-40°C to +85°C	6k	16 Ld 3x3mm TQFN	L16.3x3D

1. Refer to [TB347](#) for details about reel specifications.
2. These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.
3. For Moisture Sensitivity Level (MSL), refer to the [ISL78235R5668](#) product information page. For more information about MSL, refer to [TB363](#).

TABLE 1. KEY DIFFERENCE BETWEEN FAMILY OF PARTS

PART NUMBER	I <sub>OUT</sub> MAX (A)
ISL78233	3
ISL78234	4
ISL78235	5
ISL78235R5668	8 peak, 5 nominal ( <a href="#">Note 4</a> )

NOTE:

4. [“8A Pulsed Load Operation” on page 16.](#)



V <sub>OUT</sub>	1.0V	1.2V	1.5V	1.8V	2.5V	3.3V
C <sub>1</sub>	2 x 22μF	2 x 22μF	2 x 22μF	2 x 22μF	2 x 22μF	2 x 22μF
C <sub>2</sub> (Note 5)	3 x 22μF	3 x 22μF	3 x 22μF	2 x 22μF	2 x 22μF	2 x 22μF
C <sub>3</sub>	22pF	22pF	10pF	10pF	10pF	10pF
L <sub>1</sub>	0.22μH-0.68μH	0.33μH-0.68μH	0.33μH-0.68μH	0.33μH-0.68μH	0.47μH-0.78μH	0.47μH-0.78μH
R <sub>2</sub>	100kΩ	100kΩ	150kΩ	200kΩ	316kΩ	450kΩ
R <sub>3</sub>	150kΩ	100kΩ	100kΩ	100kΩ	100kΩ	100kΩ

5.  $C_2$  values are the minimum recommended values for ceramic capacitors. Higher capacitance may be needed based on system requirements.

**Absolute Maximum Ratings** (Reference to GND)

VIN	-0.3V to 5.8V (DC) or 7V (20ms)
EN, FS, PG, SYNC, VFB	-0.3V to VIN + 0.3V
PHASE	-1.5V (100ns)/-0.3V (DC) to 6.5V (DC) or 7V (20ms)
COMP, SS	-0.3V to 2.7V
ESD Rating	
Human Body Model (Tested per AEC-Q100-002)	5kV
Machine Model (Tested per AEC-Q100-003)	300V
Charge Device Model (Tested per AEC-Q100-011)	2kV
Latch-Up (Tested per AEC-Q100-004, Class II, Level A)	100mA

**Thermal Information**

Thermal Resistance	$\theta_{JA}$ (°C/W)	$\theta_{JC}$ (°C/W)
16 Ld TQFN Package (Notes 6, 7)	43	3.5
Operating Junction Temperature Range	-55°C to +125°C	
Storage Temperature Range	-65°C to +150°C	
Pb-Free Reflow Profile	see <a href="#">TB493</a>	

**Recommended Operating Conditions**

VIN Supply Voltage Range	2.7V to 5.5V
Load Current Range (Continuous)	0A to 5A
Pulse Load Current (<100µs; <10% duty cycle)	8A
Ambient Temperature Range	-40°C to +85°C

**CAUTION:** Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

**NOTES:**

- $\theta_{JA}$  is measured in free air with the component mounted on a high-effective thermal conductivity test board with “direct attach” features. Refer to [TB379](#).
- $\theta_{JC}$ , “case temperature” location is at the center of the exposed metal pad on the package underside.

**Electrical Specifications** Specification limits are established at the following conditions:  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ,  $V_{IN} = 3.6\text{V}$ ,  $EN = V_{IN}$ , unless otherwise noted. Typical values are at  $T_A = +25^\circ\text{C}$ . **Boldface limits apply across the operating temperature range  $-40^\circ\text{C}$  to  $+85^\circ\text{C}$ .**

PARAMETER	SYMBOL	TEST CONDITIONS	MIN (Note 8)	TYP	MAX (Note 8)	UNIT
<b>INPUT SUPPLY</b>						
VIN Undervoltage Lockout Threshold	$V_{UVLO}$	Rising, no load		2.5	<b>2.7</b>	V
		Falling, no load	<b>2.20</b>	2.45		V
Quiescent Supply Current	$I_{VIN}$	SYNC = GND, no load at the output		47		µA
		SYNC = GND, no load at the output and no switches switching		47	<b>60</b>	µA
		SYNC = VIN, $f_{SW} = 2\text{MHz}$ , no load at the output		19	<b>25</b>	mA
Shutdown Supply Current	$I_{SD}$	SYNC = GND, $V_{IN} = 5.5\text{V}$ , EN = low		4	<b>10</b>	µA
<b>OUTPUT REGULATION</b>						
Reference Voltage	$V_{REF}$		<b>0.594</b>	0.600	<b>0.606</b>	V
VFB Bias Current	$I_{VFB}$	VFB = 0.75V		0.1		µA
Line Regulation		$V_{IN} = V_O + 0.5\text{V}$ to 5.5V (minimal 2.7V)		0.2		%/V
Soft-Start Ramp Time Cycle		SS = SGND		1		ms
Soft-Start Charging Current	ISS	$V_{SS} = 0.1\text{V}$	<b>1.7</b>	2.1	<b>2.5</b>	µA
<b>OVERCURRENT PROTECTION</b>						
Current Limit Blanking Time	$t_{OCON}$			17		Clock pulses
Overcurrent and Auto Restart Period	$t_{OCCOFF}$			8		SS cycle
Positive Peak Current Limit	$I_{PLIMIT}$	$T_A = +25^\circ\text{C}$	10	12	14	A
		$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	<b>10</b>		<b>14.7</b>	A
Peak Skip Limit	$I_{SKIP}$	$T_A = +25^\circ\text{C}$	1.30	1.50	1.75	A
		$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	<b>1.30</b>		<b>1.82</b>	A
Zero Cross Threshold			<b>-275</b>		<b>375</b>	mA
Negative Current Limit	$I_{NLIMIT}$	$T_A = +25^\circ\text{C}$	-5.0	-2.8	-1.3	A
		$T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$	<b>-5.0</b>		<b>-0.6</b>	A

**Electrical Specifications** Specification limits are established at the following conditions:  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ ,  $V_{IN} = 3.6\text{V}$ ,  $EN = V_{IN}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}\text{C}$ . **Boldface limits apply across the operating temperature range  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ .** (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN ( <a href="#">Note 8</a> )	TYP	MAX ( <a href="#">Note 8</a> )	UNIT
COMPENSATION						
Error Amplifier Transconductance		COMP = VDD, internal compensation		125		μA/V
		External compensation		130		μA/V
Transresistance	RT		0.10	0.12	0.14	Ω
MOSFET						
P-Channel ON-Resistance		V <sub>IN</sub> = 5V, I <sub>O</sub> = 200mA	26	35	50	mΩ
		V <sub>IN</sub> = 2.7V, I <sub>O</sub> = 200mA	38	52	78	mΩ
N-Channel ON-Resistance		V <sub>IN</sub> = 5V, I <sub>O</sub> = 200mA	5	11	20	mΩ
		V <sub>IN</sub> = 2.7V, I <sub>O</sub> = 200mA	8	15	31	mΩ
PHASE						
PHASE Maximum Duty Cycle				100		%
PHASE Minimum On-Time		SYNC = High			100	ns
OSCILLATOR						
Nominal Switching Frequency	f <sub>SW</sub>	FS = V <sub>IN</sub>	1730	2000	2350	kHz
		FS with RS = 402kΩ		420		kHz
		FS with RS = 42.2kΩ		4200		kHz
SYNC Logic LOW to HIGH Threshold			0.67	0.75	0.84	V
SYNC Logic Hysteresis			0.1	0.17	0.2	V
SYNC Logic Input Leakage Current		SYNC = 3.6V		3.7	5	μA
POWER-GOOD (PG)						
Output Low Voltage		I <sub>PG</sub> = 1mA			0.3	V
PG Delay Time (Rising Edge)		Time from V <sub>OUT</sub> reached regulation	0.5	1	2	ms
PG Delay Time (Falling Edge)				6.5		μs
PG Pin Leakage Current		PG = V <sub>IN</sub>		0.01	0.1	μA
OVP PG Rising Threshold				0.80		V
UVP PG Rising Threshold			80	85	90	%
UVP PG Hysteresis				5.5		%
EN						
Logic Input Low ( <a href="#">Note 9</a> )	EN_VIL				0.4	V
Logic Input High	EN_VIH		0.9			V
EN Logic Input Leakage Current		EN = 3.6V		0.1	1	μA
OVER-TEMPERATURE PROTECTION						
Thermal Shutdown		Temperature rising		150		°C
Thermal Shutdown Hysteresis		Temperature falling		25		°C

## NOTES:

- Compliance to datasheet limits is assured by one or more methods: production test, characterization, and/or design.
- EN should be held below the EN\_VIL until  $V_{IN}$  exceeds  $V_{UVLO}$  rising.

## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $EN = V_{DD}$ ,  $SYNC = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{SW} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A}$  to  $8\text{A}$ .

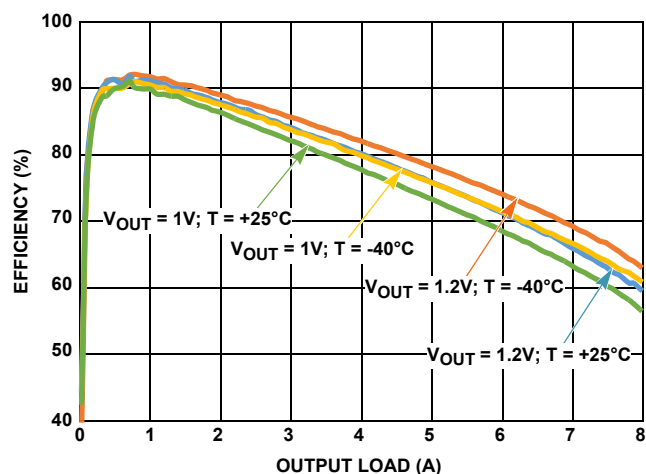


FIGURE 5. EFFICIENCY vs LOAD ( $V_{IN} = 2.7\text{V}$ )

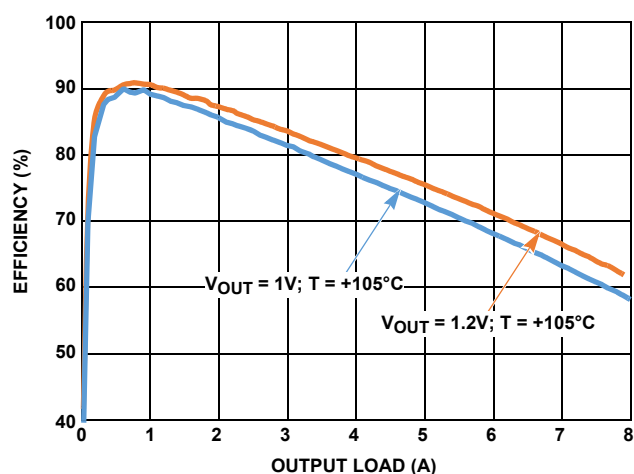


FIGURE 6. EFFICIENCY vs LOAD ( $V_{IN} = 3\text{V}$ )

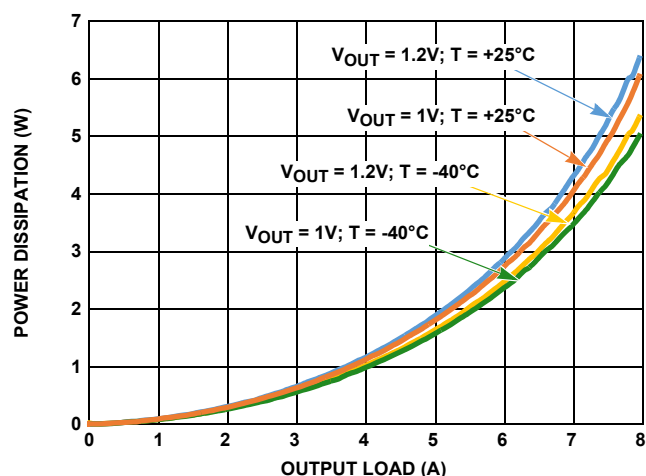


FIGURE 7. POWER DISSIPATION vs LOAD ( $V_{IN} = 2.7\text{V}$ )

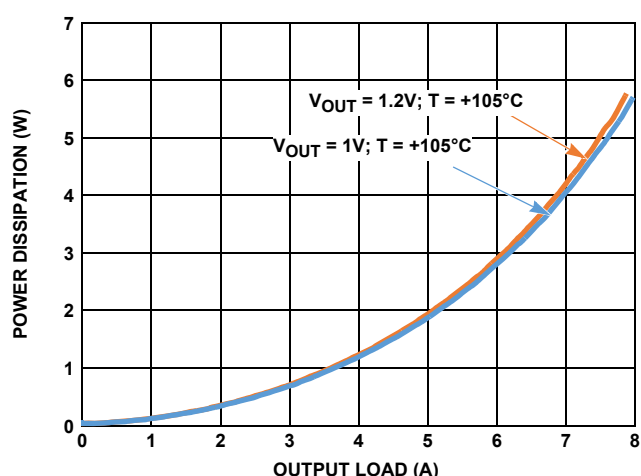


FIGURE 8. POWER DISSIPATION vs LOAD ( $V_{IN} = 3\text{V}$ )

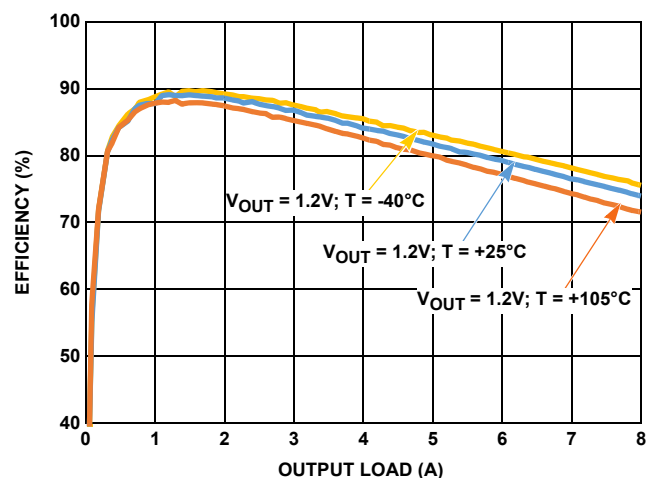


FIGURE 9. EFFICIENCY vs LOAD ( $V_{IN} = 5\text{V}$ )

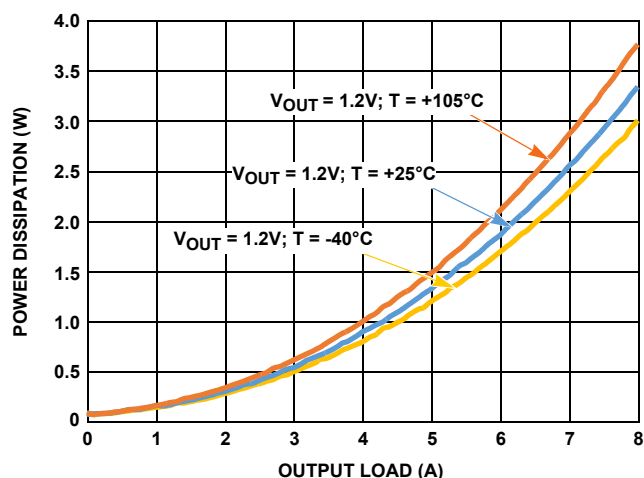


FIGURE 10. POWER DISSIPATION vs LOAD ( $V_{IN} = 5\text{V}$ )



## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $\text{EN} = V_{DD}$ ,  $\text{SYNC} = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{\text{SW}} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A to } 8\text{A}$ . (Continued)

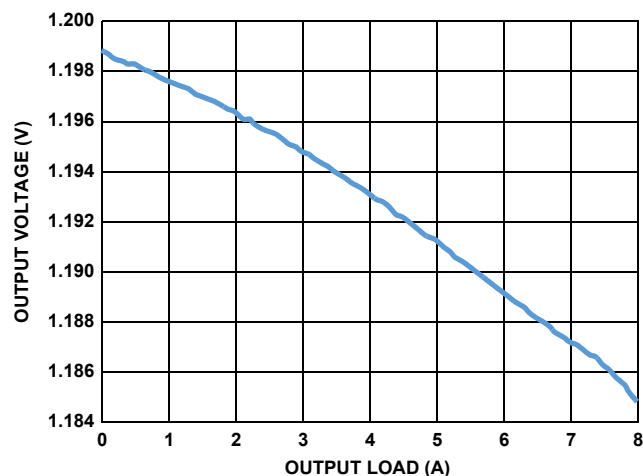


FIGURE 11.  $V_{OUT}$  REGULATION vs LOAD ( $V_{IN} = 3\text{V}$ )

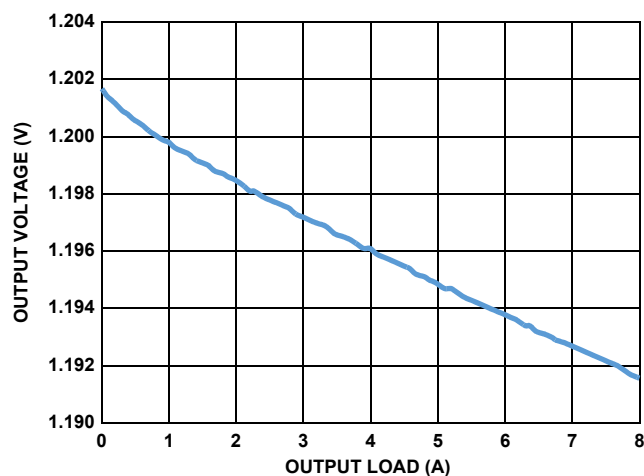


FIGURE 12.  $V_{OUT}$  REGULATION vs LOAD ( $V_{IN} = 5\text{V}$ )

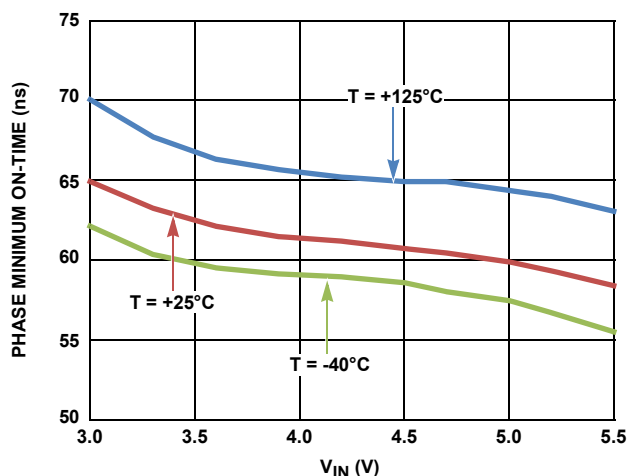


FIGURE 13. PHASE MINIMUM ON-TIME vs  $V_{IN}$

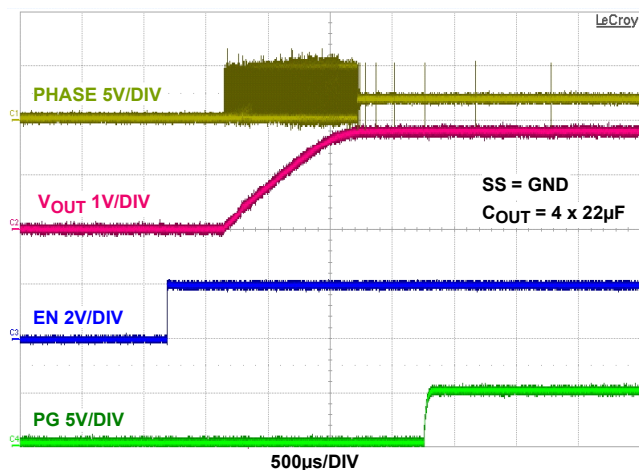


FIGURE 14. EN START-UP AT NO LOAD ( $\text{SYNC} = \text{GND}$ )

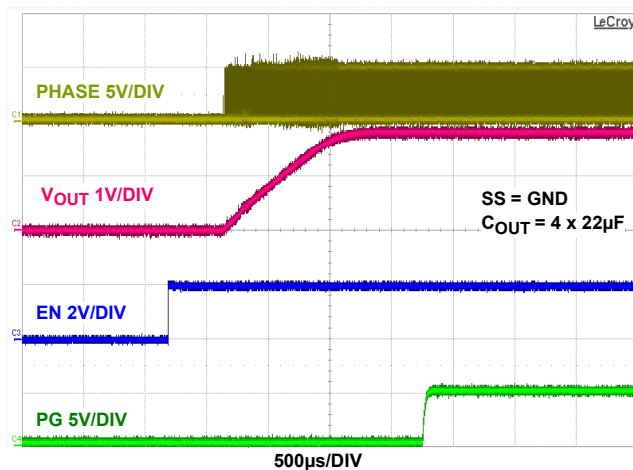


FIGURE 15. EN START-UP AT NO LOAD ( $\text{SYNC} = V_{DD}$ )

## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $\text{EN} = V_{DD}$ ,  $\text{SYNC} = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{\text{SW}} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A to } 8\text{A}$ . (Continued)

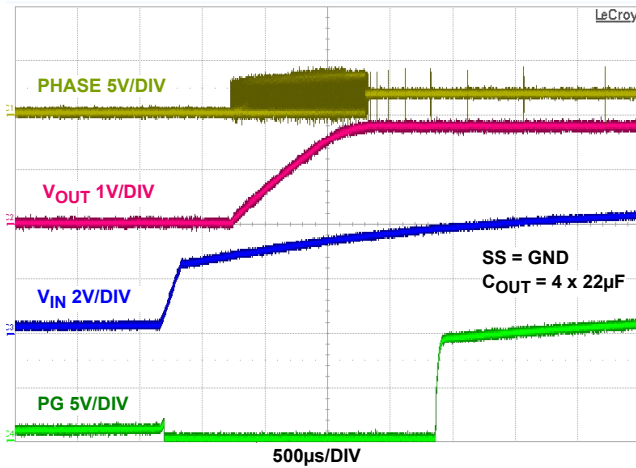


FIGURE 16.  $V_{IN}$  START-UP AT NO LOAD ( $\text{SYNC} = \text{GND}$ )

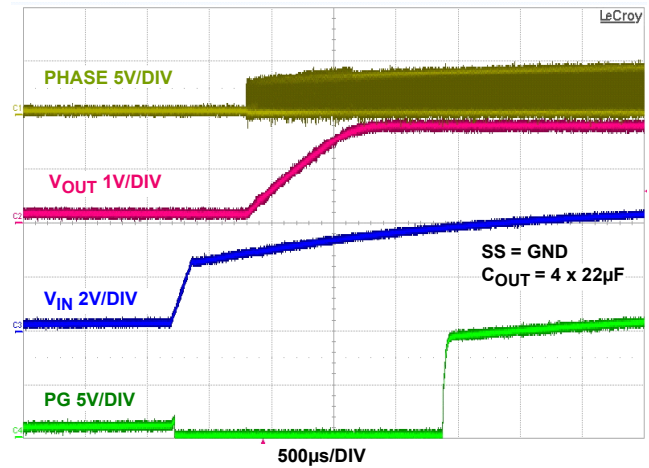


FIGURE 17.  $V_{IN}$  START-UP AT NO LOAD ( $\text{SYNC} = V_{DD}$ )

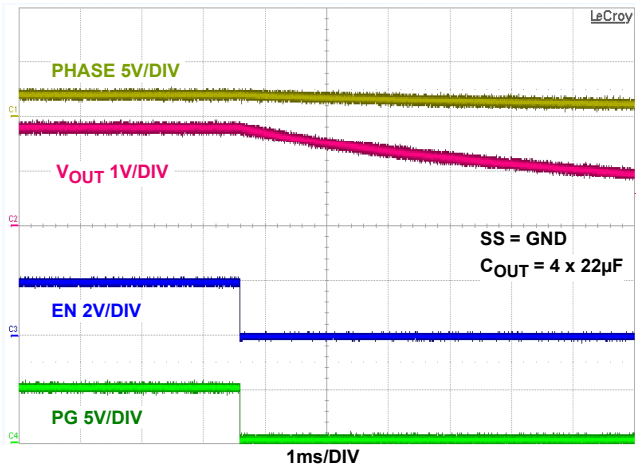


FIGURE 18.  $\text{EN}$  SHUTDOWN AT NO LOAD ( $\text{SYNC} = \text{GND}$ )

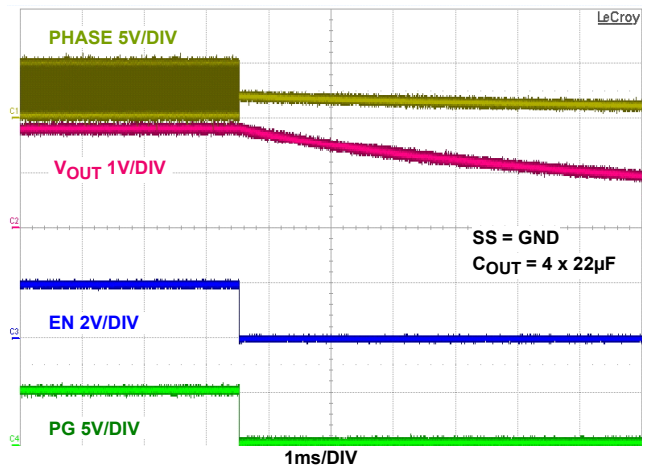


FIGURE 19.  $\text{EN}$  SHUTDOWN AT NO LOAD ( $\text{SYNC} = V_{DD}$ )

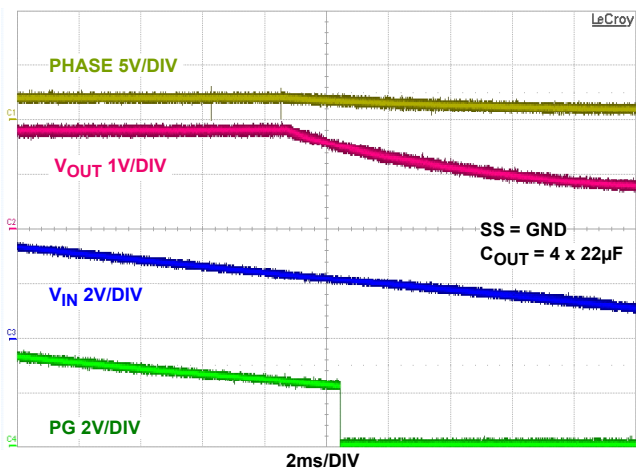


FIGURE 20.  $V_{IN}$  SHUTDOWN AT NO LOAD ( $\text{SYNC} = \text{GND}$ )

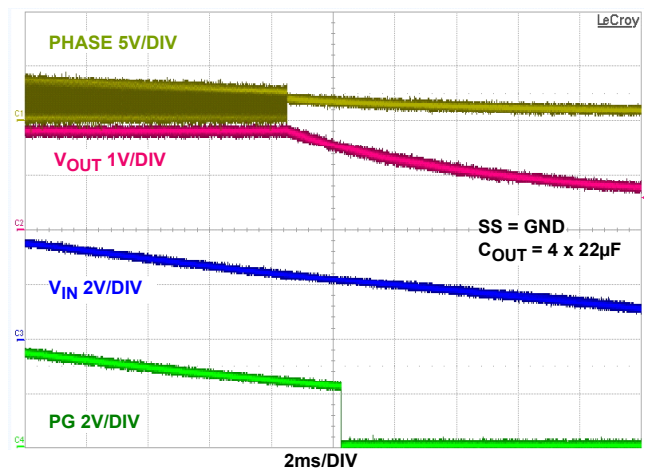


FIGURE 21.  $V_{IN}$  SHUTDOWN AT NO LOAD ( $\text{SYNC} = V_{DD}$ )

## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $EN = V_{DD}$ ,  $SYNC = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{SW} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A to } 8\text{A}$ . (Continued)

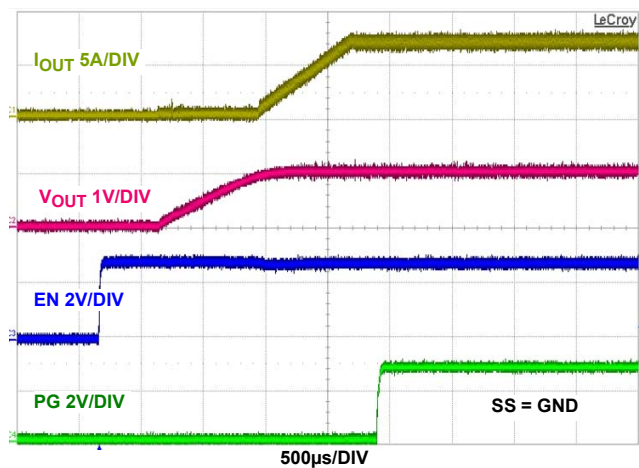


FIGURE 22. EN START-UP AT 8A LOAD

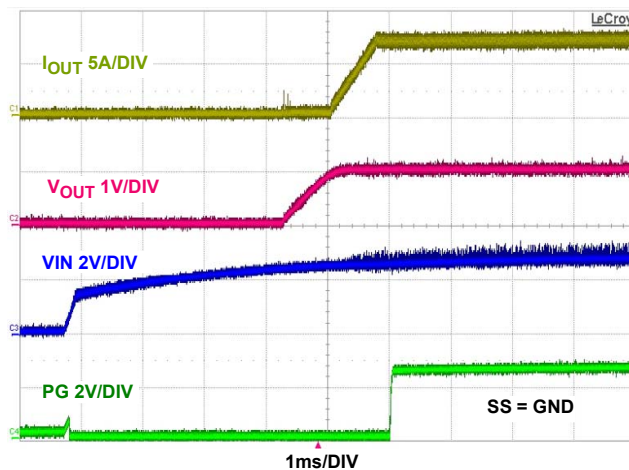
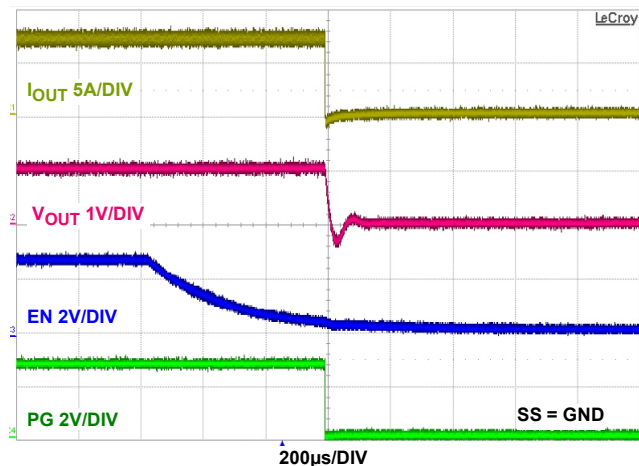
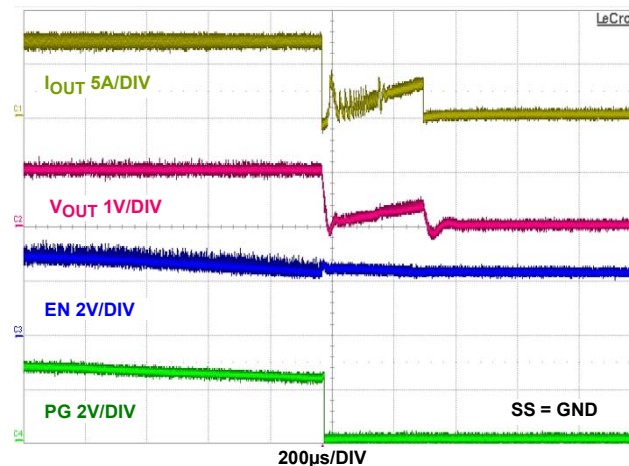
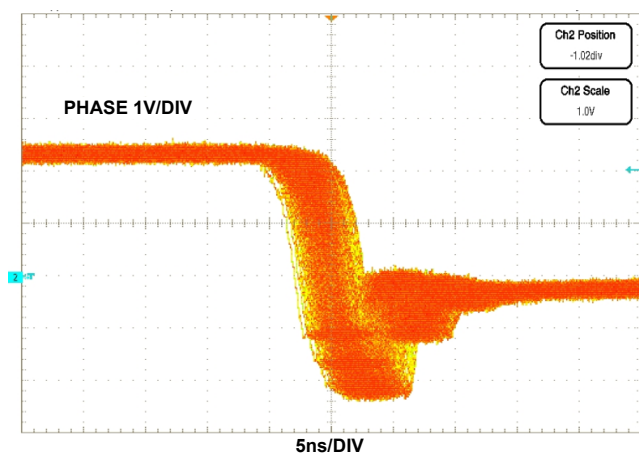
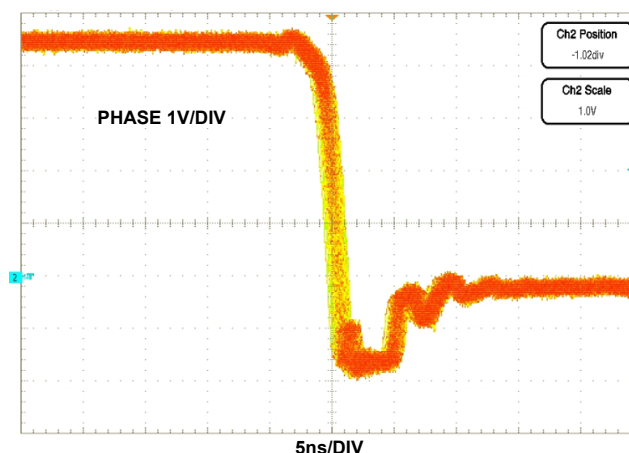
FIGURE 23.  $V_{IN}$  START-UP AT 8A LOAD

FIGURE 24. EN SHUTDOWN AT 8A LOAD

FIGURE 25.  $V_{IN}$  SHUTDOWN AT 8A LOADFIGURE 26. JITTER AT 8A LOAD;  $V_{IN} = 3\text{V}$ FIGURE 27. JITTER AT 8A LOAD;  $V_{IN} = 5\text{V}$



## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $\text{EN} = V_{DD}$ ,  $\text{SYNC} = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{\text{SW}} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A}$  to  $8\text{A}$ . (Continued)

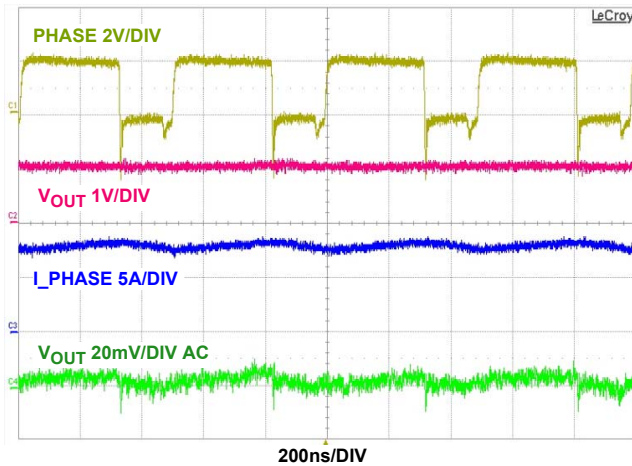


FIGURE 28. STEADY STATE AT 8A LOAD;  $V_{IN} = 2.7\text{V}$

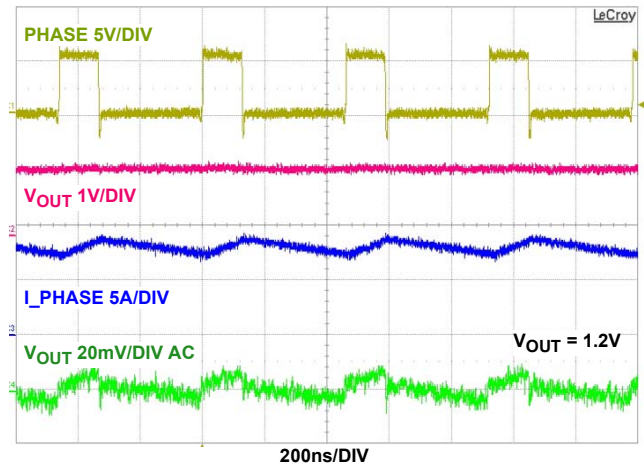


FIGURE 29. STEADY STATE AT 8A LOAD;  $V_{IN} = 5.5\text{V}$

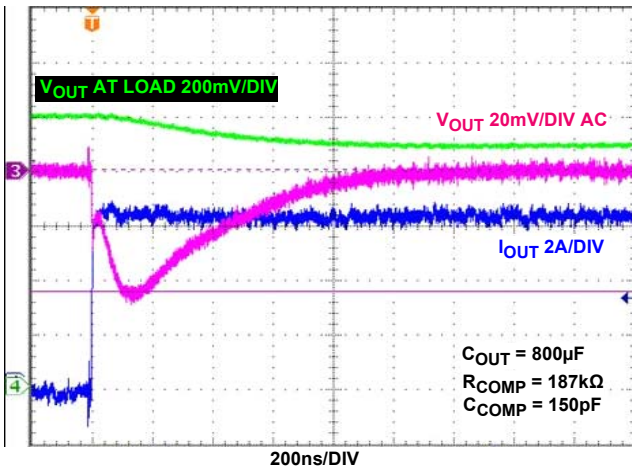


FIGURE 30. LOAD TRANSIENT  $0\text{A}$  TO  $6\text{A}$ ;  $100\text{A}/\mu\text{s}$

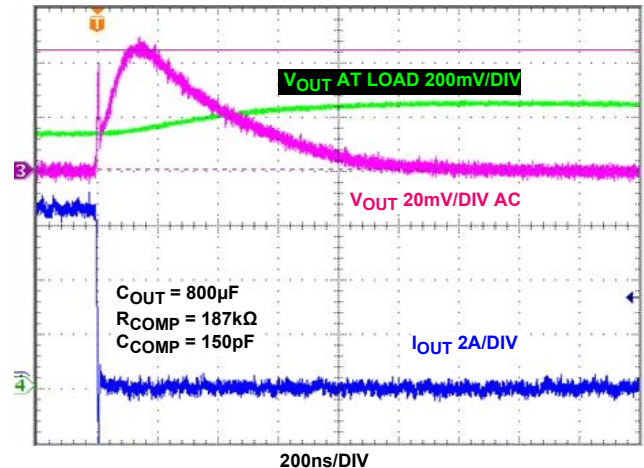


FIGURE 31. LOAD TRANSIENT  $6\text{A}$  TO  $0\text{A}$ ;  $100\text{A}/\mu\text{s}$

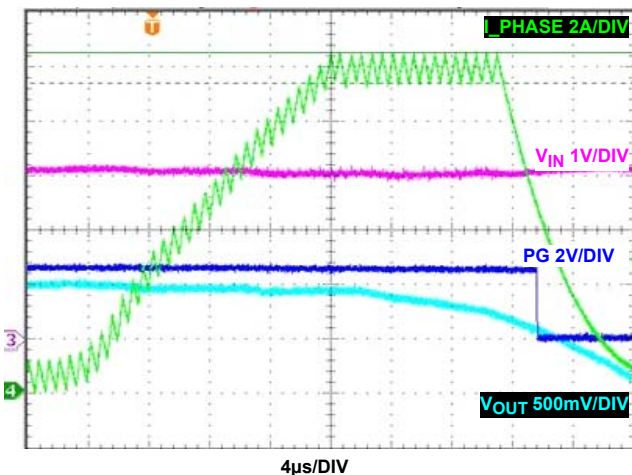


FIGURE 32. OUTPUT SHORT-CIRCUIT PROTECTION

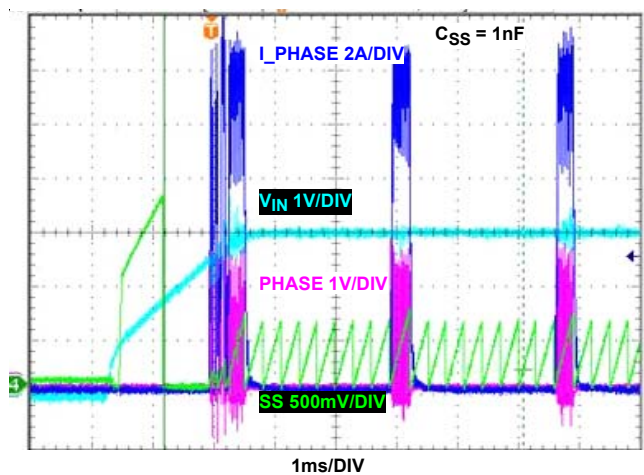


FIGURE 33. START UP INTO SHORT-CIRCUIT LOAD

## Typical Operating Performance

Unless otherwise noted, operating conditions are:  $T_A = +25^\circ\text{C}$ ,  $V_{IN} = V_{DD} = 3\text{V}$ ,  $V_{OUT} = 1.0\text{V}$ ,  $\text{EN} = V_{DD}$ ,  $\text{SYNC} = V_{DD}$ ,  $L = 0.33\mu\text{H}$ ,  $f_{\text{SW}} = 2\text{MHz}$ ,  $C_{IN} = 4 \times 22\mu\text{F}$ ,  $C_{OUT} = 4 \times 47\mu\text{F}$ ,  $I_{OUT} = 0\text{A}$  to  $8\text{A}$ . (Continued)

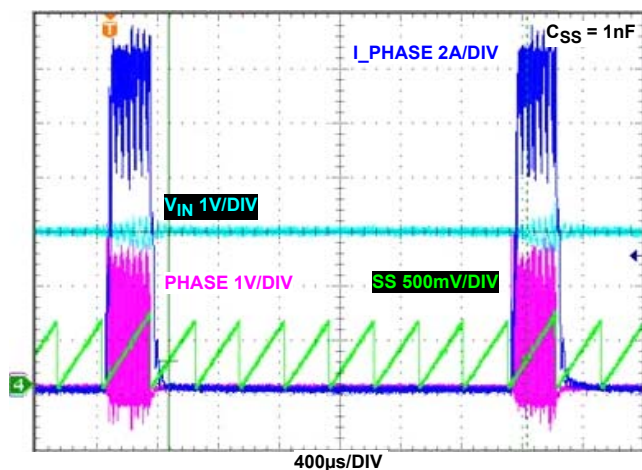


FIGURE 34. SHORT-CIRCUIT HICCUP WAVEFORM

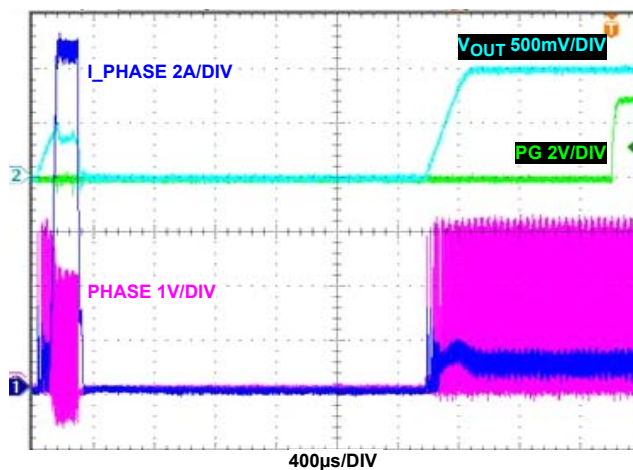


FIGURE 35. SHORT-CIRCUIT HICCUP RECOVERY TO 1A LOAD

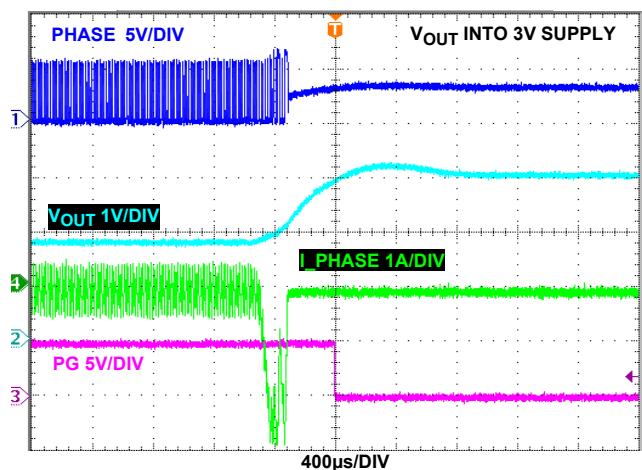


FIGURE 36. OVERVOLTAGE PROTECTION

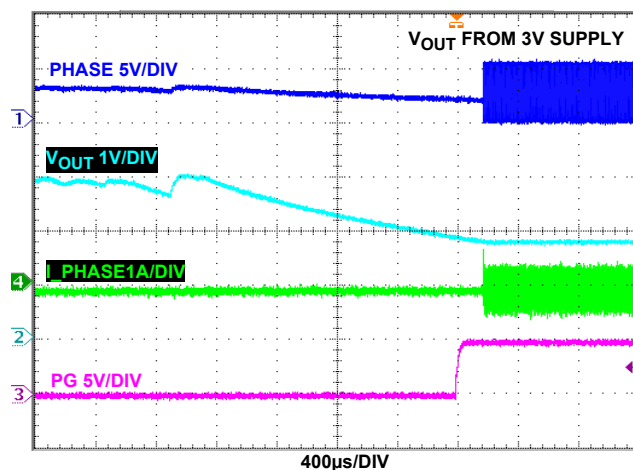


FIGURE 37. OVERVOLTAGE RECOVERY

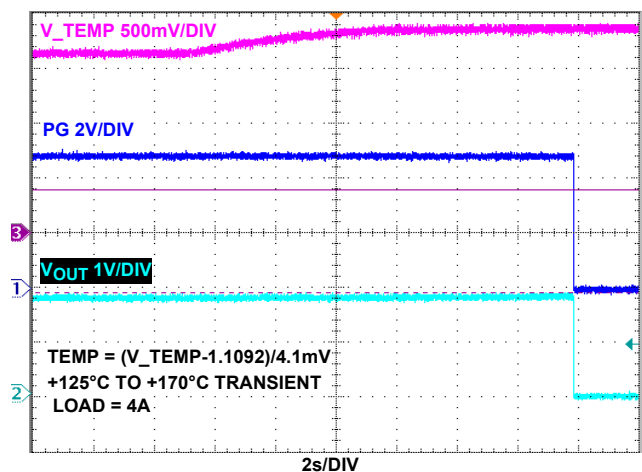


FIGURE 38. OVER-TEMPERATURE PROTECTION

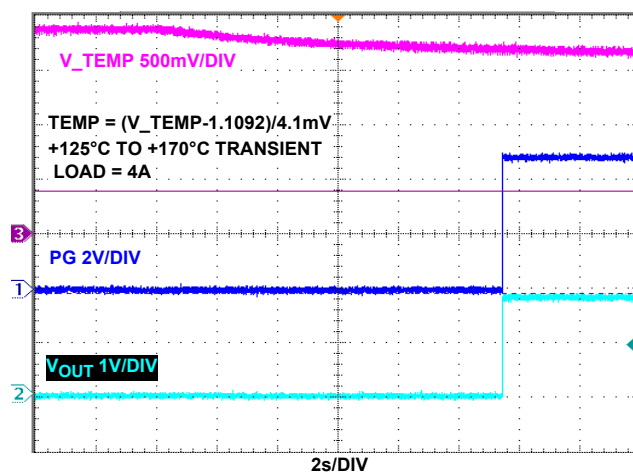


FIGURE 39. OVER-TEMPERATURE RECOVERY

## Theory of Operation

The ISL78235R5668 is a step-down switching regulator optimized for automotive point-of-load powered applications. The regulator operates at a default 2MHz fixed switching frequency for high efficiency and smaller form factor while staying out of the AM frequency band. By connecting a resistor from FS to SGND, the operational frequency is adjustable in the range of 500kHz to 4MHz. At light load, the regulator reduces the switching frequency by operating in Pulse Frequency Modulation (PFM) mode, unless forced to operate in fixed frequency PWM mode, to minimize the switching loss and to maximize the battery life. The quiescent current when the output is not loaded is typically only 45µA. The supply current is typically only 3.8µA when the regulator is shut down.

### PWM Control Scheme

Pulling the SYNC pin HI (>0.8V) forces the converter into PWM mode, regardless of output current, bypassing the PFM operation at light load. The ISL78235R5668 uses the current-mode Pulse-Width Modulation (PWM) control scheme for fast transient response and pulse-by-pulse current limiting (see [Figure 3 on page 2](#)). The current loop consists of the oscillator, the PWM comparator, current sensing circuit, and the slope compensation for the current loop stability. The slope compensation is  $440\text{mV}/T_s$  ( $T_s$  is the switching period), which changes proportionally with frequency. The gain for the current sensing circuit is typically  $120\text{mV}/\text{A}$ . The control reference for the current loops comes from the Error Amplifier's (EAMP) output.

The PWM operation is initialized by the clock from the oscillator. The P-channel MOSFET is turned on at the beginning of a PWM cycle and the current in the MOSFET starts to ramp up. When the sum of the current amplifier CSA and the slope compensation reaches the control reference of the current loop, the PWM comparator COMP sends a signal to the PWM logic to turn off the PFET and turn on the N-channel MOSFET. The NFET stays on until the end of the PWM cycle. [Figure 40](#) shows the typical operating waveforms during the PWM operation. The dotted lines on  $V_{CSA}$  illustrate the sum of the slope compensation ramp and the current-sense amplifier's CSA output.

The output voltage is regulated by controlling the  $V_{EAMP}$  voltage to the current loop. The bandgap circuit outputs a 0.6V reference voltage to the voltage loop. The feedback signal comes from the VFB pin. The soft-start block only affects the operation during the start-up and is discussed separately. The error amplifier is a transconductance amplifier that converts the voltage error signal to a current output. The voltage loop is internally compensated with the 55pF and 100kΩ RC network. The maximum EAMP voltage output is precisely clamped to 2.5V.

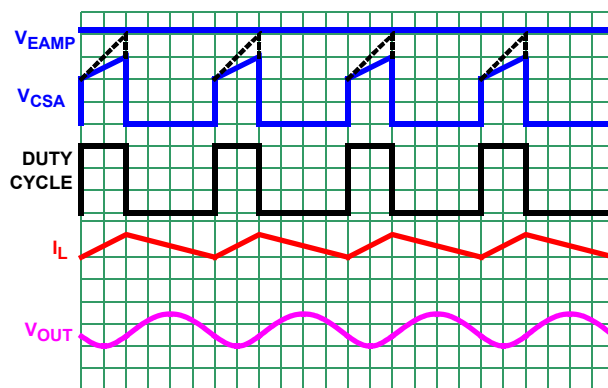


FIGURE 40. PWM OPERATION WAVEFORMS

### Skip Mode (PFM)

Pulling the SYNC pin low (<0.4V) forces the converter into PFM mode. The ISL78235R5668 enters a pulse-skipping mode at light load to minimize the switching loss by reducing the switching frequency. [Figure 41 on page 15](#) illustrates Skip mode operation. A zero-cross sensing circuit shown in [Figure 3 on page 2](#) monitors the NFET current for zero crossing. When 16 consecutive cycles are detected, the regulator enters Skip mode. During the sixteen detecting cycles, the current in the inductor is allowed to become negative. The counter is reset to zero when the current in any cycle does not cross zero.

Once Skip mode is entered, the pulse modulation starts being controlled by the Skip comparator shown in [Figure 3 on page 2](#). Each pulse cycle is still synchronized by the PWM clock. The PFET is turned on at the clock's rising edge and turned off when the output is higher than 1.2% of the nominal regulation or when its current reaches the peak skip current limit value. Then, the inductor current is discharging to 0A and stays at zero (the internal clock is disabled), and the output voltage reduces gradually due to the load current discharging the output capacitor. When the output voltage drops to the nominal voltage, the PFET will be turned on again at the rising edge of the internal clock as it repeats the previous operations.

The regulator resumes normal PWM mode operation when the output voltage drops 1.2% below the nominal voltage.



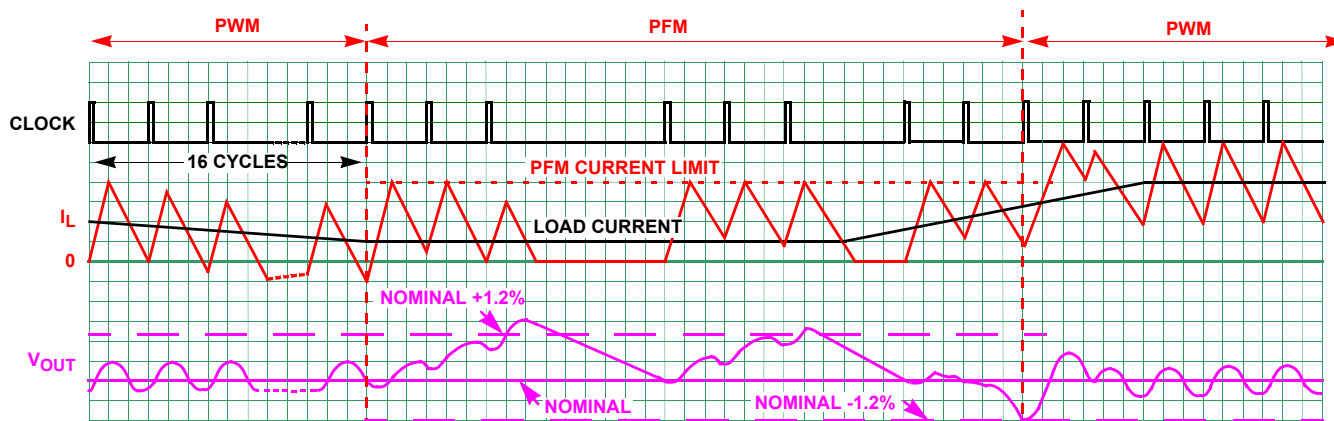


FIGURE 41. SKIP MODE OPERATION WAVEFORMS

## Frequency Adjust

The frequency of operation is fixed at 2MHz when FS is tied to VIN. The switching frequency is adjustable in the range from 500kHz to 4MHz with a resistor from FS to SGND according to [Equation 1](#):

$$R_{FS}[k\Omega] = \frac{220 \cdot 10^3}{f_{OSC}[kHz]} - 14 \quad (\text{EQ. 1})$$

The ISL78235R5668 also has frequency synchronization capability by connecting the SYNC pin to an external square pulse waveform. The frequency synchronization feature will synchronize the positive edge trigger and its switching frequency up to 4MHz. The synchronization positive pulse width should be 100ns or greater for proper operation. The minimum external SYNC frequency is half of the free running oscillator frequency (either the default 2MHz when FS tied to VIN or determined by the resistor from FS to SGND).

## Overcurrent Protection

The overcurrent protection is realized by monitoring the CSA output with the OCP comparator, as shown in [Figure 3 on page 2](#). The current sensing circuit has a gain of 120mV/A typical, from the PFET current to the CSA output. When the CSA output reaches the threshold, the OCP comparator is tripped to turn off the PFET immediately. The overcurrent function protects the switching converter from a shorted output by monitoring the current flowing through the upper MOSFET.

Upon detection of an overcurrent condition, the upper MOSFET is immediately turned off and is not turned on again until the next switching cycle. Upon detection of the initial overcurrent condition, the overcurrent fault counter is set to 1. The OC fault counter is incremented if another overcurrent condition is detected on the subsequent cycle. If there are 17 sequential OC fault detections, the regulator is shut down under an overcurrent fault condition. An overcurrent fault condition results in the regulator attempting to restart in a hiccup mode within the delay of eight soft-start periods. At the end of the 8th soft-start wait period, the fault counters are reset and soft-start is attempted again. If the overcurrent condition goes away during the delay of eight soft-start periods, the output will resume back into regulation point after Hiccup mode expires.

## Negative Current Protection

Similar to overcurrent, the negative current protection is realized by monitoring the current across the low-side NFET, as shown in [Figure 3 on page 2](#). When the valley point of the inductor current reaches -3A for four consecutive cycles, both PFET and NFET are off. A 100Ω discharge circuit in parallel to the NFET activates to discharge the output into regulation. The regulator resumes switching operation when output is within regulation. The regulator will be in PFM for 20μs before switching to PWM if necessary.

## PG

PG is an open-drain output of a window comparator that continuously monitors the buck regulator output voltage. PG is actively held low when EN is low and during the buck regulator soft-start period. After the soft-start period and a 1ms delay, PG becomes high impedance as long as the output voltage is within nominal regulation voltage set by VFB. When the voltage at the FB pin drops 15% below 0.6V or rises above 0.8V, the ISL78235R5668 pulls PG low. Any fault condition forces PG low until the fault condition is cleared and after soft-start completes. For logic level output voltages, connect an external pull-up resistor between PG and VIN. A 100kΩ resistor works well in most applications.

## UVLO

When the input voltage is below the Undervoltage Lockout (UVLO) threshold (2.5V typical), the regulator is disabled.

## Soft Start-Up

The soft start-up circuit reduces the inrush current during power-up. The soft-start block outputs a ramp reference to the input of the error amplifier. This voltage ramp limits the slew rate of inductor current as well as the output voltage, so that the output voltage rises in a controlled fashion. When VFB is less than 0.1V at the beginning of the soft-start, the switching frequency is reduced to 200kHz, so that the output can start-up smoothly at light load condition. During soft-start, the IC operates in Skip mode to support prebiased output condition.

Tie SS to SGND for internal soft-start (1ms typical). Connect a capacitor from SS to SGND to adjust the soft-start time. This capacitor, along with an internal 2.1μA current source, sets the soft-start interval of the converter,  $t_{SS}$  as shown by [Equation 2](#).

$$C_{SS}[\mu F] = 3.1 \cdot t_{SS}[s] \quad (\text{EQ. 2})$$

$C_{SS}$  must be less than 33nF to ensure proper soft-start reset after fault condition.

## Enable

The Enable (EN) input allows the user to control the turning on or off of the regulator for purposes such as power-up sequencing or minimizing power dissipation when the output is not needed. When the regulator is enabled, there is typically a 600μs delay for waking up the bandgap reference and then the soft start-up begins. EN should be held below the EN\_VIL until  $V_{IN}$  exceeds  $V_{UVLO}$  rising.

## Discharge Mode (Soft-Stop)

When a transition to shutdown mode occurs, (EN low or fault condition) or the  $V_{IN}$  UVLO is set, the output is discharged to GND through an internal 100Ω switch on the PHASE pin.

## Power MOSFETs

The power MOSFETs are optimized for highest efficiency. The ON-resistance for the PFET is typically 35mΩ and the ON-resistance for the NFET is typically 11mΩ.

## 100% Duty Cycle

The ISL78235R5668 features a 100% duty cycle operation to maximize the battery operation life and provide very low dropout down to the minimum operating voltage. When the battery voltage drops to a level that the ISL78235R5668 can no longer maintain the regulation at the output, the regulator completely turns on the PFET. The maximum dropout voltage under the 100% duty cycle operation is the product of the load current and the ON-resistance of the PFET.

## Thermal Shutdown

The ISL78235R5668 has built-in over-temperature thermal protection. When the internal temperature reaches +150°C, the regulator completely shuts down. As the temperature drops to +125°C, the ISL78235R5668 resumes operation after a soft-start cycle.

# Applications Information

## 8A Pulsed Load Operation

The ISL78235R5668 is intended for 5A continuous output current operation. However, the peak current limit threshold of the overcurrent comparator is set to allow up to 8A of load current without going into Overcurrent Protection (OCP) for automotive point-of-load regulation applications.

It is not recommended to operate the ISL78235R5668 above 5A continuous operation. The peak current limit set point is intended to allow pulse load currents that do not exceed 100μs and 10% duty cycle for applications that require high peak transient

current while the nominal load is 5A or less. Choose the inductor value accordingly such that the peak ripple current does not trigger the current limit threshold (12A typical). The overcurrent protection circuitry prevents continuous operation in an overcurrent condition. The overcurrent protection circuitry is not active until the output current exceeds the current limit threshold. Because the current limit threshold is much higher than 5A, a fault condition that causes the output current to nominally be above 5A but below the current limit threshold is not protected by the IC and such operating condition should be avoided.

For applications where the load transient has a very fast di/dt and large amplitude, the input decoupling capacitance must provide the instantaneous current for the buck regulator. As a result, there will be undershoot of the input voltage during the transient duration. The voltage at the VDD pin of the ISL78235R5668 must stay above the UVLO threshold for continuous operation. If the input voltage crosses the UVLO threshold, a power on reset is initiated. Adequate input capacitance is necessary to support the application load transient condition.

## Output Inductor and Capacitor Selection

During steady state and transient operation, the ISL78235R5668 typically uses a 0.33μH to 0.78μH output inductor. Higher or lower inductor values can be used to optimize the total converter system performance. For example, in order to decrease the inductor current ripple and output voltage ripple for a higher output voltage 3.3V application, the output inductor value can be increased. It is recommended to set the ripple inductor current to approximately 30% of the maximum output current for optimized performance. The inductor ripple current can be expressed as shown in [Equation 3](#):

$$\Delta I = \frac{V_{OUT} \cdot \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}{L \cdot f_{SW}} \quad (\text{EQ. 3})$$

The inductor's saturation current rating needs to be larger than the "Positive Peak Current Limit" on [page 6](#) specified in the electrical specification table. The ISL78235R5668 has a typical peak current limit of 12A. The inductor saturation current needs to be over 12A for proper operation.

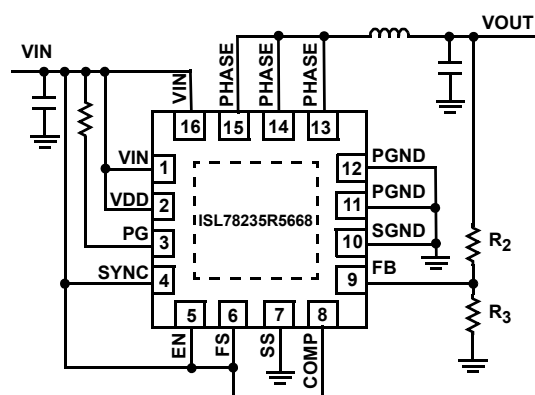
The ISL78235R5668 uses an internal compensation network for regulator stability and the output capacitor value is dependent on the output voltage. The recommended ceramic capacitors are low ESR X7R rated or better. The recommended minimum output capacitor values are shown in [Table 2 on page 5](#).

[Table 2](#) shows the minimum output capacitor value is given for the different output voltages to make sure that the whole converter system is stable. Additional output capacitance should be added for better performance in applications where high load transient or low output ripple is required. It is recommended to check the system level performance along with the simulation model.



## Output Voltage Selection

The output voltage of the regulator is programmed with an external resistor divider that is used to scale the output voltage relative to the internal reference voltage (0.6V) and fed back to the inverting input of the error amplifier FB pin (see [Figure 42](#)).



**FIGURE 42. PROGRAMMING OUTPUT VOLTAGE WITH  $R_2$  AND  $R_3$**

The output voltage programming resistor  $R_2$  (from VOUT to FB) will depend on the value chosen for the feedback resistor and the desired output voltage of the regulator. The value for the feedback resistor,  $R_3$  (from FB to GND), is typically between 10k $\Omega$  and 100k $\Omega$ .  $R_2$  is chosen as shown in [Equation 4](#).

$$R_2 = R_3 \left( \frac{V_{OUT}}{V_{FB}} - 1 \right) \quad (\text{EQ. 4})$$

where  $V_{FB} = 0.6V$  and  $V_{OUT}$  is the output voltage.

There is a leakage current from VIN to PHASE. Renesas recommends to preload the output with 10μA minimum for accurate output voltage. For improved loop stability performance, add 10pF to 22pF in parallel with R<sub>2</sub>. Check loop analysis before use in application. See [“Loop Compensation Design”](#) for more information.

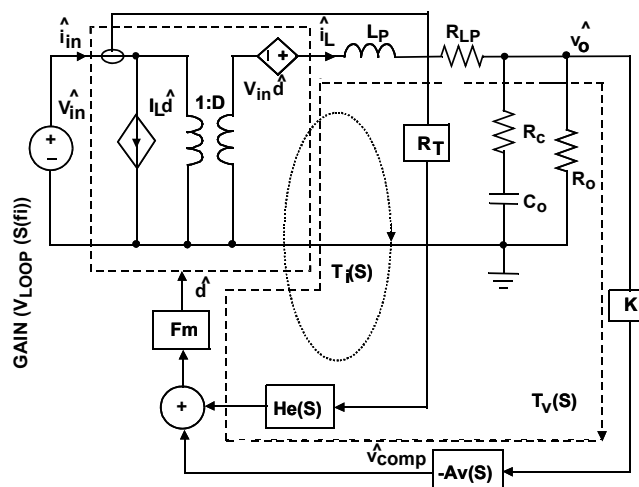
## Input Capacitor Selection

The main functions for the input capacitor are to provide decoupling of the parasitic inductance and to provide a filtering function to prevent the switching current flowing back to the input rail. Two 22 $\mu$ F low ESR X7R rated ceramic capacitors in parallel with a 0.1 $\mu$ F high frequency decoupling capacitor placed very close to the VIN/VDD and SGND/PGND pins is a good starting point for the input capacitor selection.

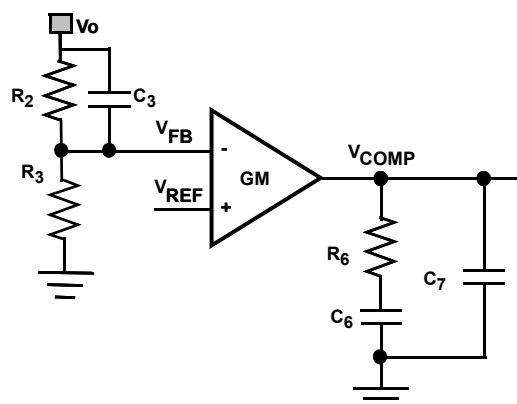
## Loop Compensation Design

When COMP is not connected to VDD, the COMP pin is active for external loop compensation. The ISL78235R5668 uses constant frequency peak current mode control architecture to achieve a fast loop transient response. An accurate current sensing circuit in parallel with the upper MOSFET is used for peak current control signal and overcurrent protection. The inductor is not considered as a state variable since its peak current is constant and the system becomes a single order system. It is much easier to design a type II compensator to stabilize the loop than to implement voltage mode control. Peak current mode control has an inherent input voltage feed-forward function to achieve good

line regulation. [Figure 43](#) shows the small signal model of the synchronous buck regulator.



**FIGURE 43. SMALL SIGNAL MODEL OF SYNCHRONOUS BUCK REGULATOR**



**FIGURE 44. TYPE II COMPENSATOR**

**Figure 44** shows the type II compensator and its transfer function is expressed as **Equation 5**:

$$A_V(S) = \frac{\hat{v}_{\text{comp}}}{v_{\text{FB}}} = \frac{GM \cdot R_3}{(C_6 + C_7) \cdot (R_2 + R_3)} \frac{\left(1 + \frac{S}{\omega_{cz1}}\right) \left(1 + \frac{S}{\omega_{cz2}}\right)}{S \left(1 + \frac{S}{\omega_{cp1}}\right) \left(1 + \frac{S}{\omega_{cp2}}\right)} \quad (\text{EO. 5})$$

where

$${}^{(i)}\omega_{cz1} = \frac{1}{R_6 C_6}, \quad {}^{(i)}\omega_{cz2} = \frac{1}{R_2 C_3}, \quad {}^{(i)}\omega_{cp1} = \frac{C_6 + C_7}{R_6 C_6 C_7}, \quad {}^{(i)}\omega_{cp2} = \frac{R_2 + R_3}{C_3 R_2 R_3}$$

**Compensator design goal:**

**High DC gain**

Choose Loop bandwidth  $f_c \sim 100\text{kHz}$  or less

Gain margin:  $>10\text{dB}$

Phase margin:  $>40^\circ$

The compensator design procedure is as follows:

The loop gain at crossover frequency of  $f_c$  has a unity gain. Therefore, the compensator resistance  $R_6$  is determined by [Equation 6](#).

$$R_6 = \frac{2\pi f_c V_o C_o R_t}{GM \cdot V_{FB}} = 13.7 \times 10^3 \cdot f_c V_o C_o \quad (\text{EQ. 6})$$

Where  $GM$  is the transconductance,  $g_m$ , of the voltage error amplifier and  $R_t$  is the gain of the current sense amplifier. Compensator capacitors  $C_6$  and  $C_7$  are given by [Equation 7](#).

$$C_6 = \frac{R_o C_o}{R_6} = \frac{V_o C_o}{I_o R_6}, C_7 = \max\left(\frac{R_o C_o}{R_6}, \frac{1}{\pi f_s R_6}\right) \quad (\text{EQ. 7})$$

Put one compensator pole at zero frequency to achieve high DC gain, and put another compensator pole at either ESR zero frequency or half switching frequency, whichever is lower in [Equation 7](#). An optional zero can boost the phase margin.  $\omega_{CZ2}$  is a zero due to  $R_2$  and  $C_3$ .

Put compensator zero 2 to 5 times  $f_c$ :

$$C_3 = \frac{1}{\pi f_c R_2} \quad (\text{EQ. 8})$$

Example:  $V_{IN} = 5V$ ,  $V_o = 1.8V$ ,  $I_o = 5A$ ,  $f_{SW} = 2MHz$ ,  $R_2 = 200k\Omega$ ,  $R_3 = 100k\Omega$ ,  $C_o = 2 \times 22\mu F / 10m\Omega$ ,  $L = 0.68\mu H$ ,  $f_c = 100kHz$ , then compensator resistance  $R_6$ :

$$R_6 = 13.7 \times 10^3 \cdot 100kHz \cdot 1.8V \cdot 44\mu F = 108k\Omega \quad (\text{EQ. 9})$$

It is acceptable to use  $107k\Omega$  as the closest standard value for  $R_6$ .

$$C_6 = \frac{1.8V \cdot 44\mu F}{5A \cdot 107k\Omega} = 148pF \quad (\text{EQ. 10})$$

$$C_7 = \max\left(\frac{10m\Omega \cdot 44\mu F}{107k\Omega}, \frac{1}{\pi \cdot 2MHz(107k\Omega)}\right) = (4.1pF, 1.5pF) \quad (\text{EQ. 11})$$

It is also acceptable to use the closest standard values for  $C_6$  and  $C_7$ . There is approximately  $3pF$  parasitic capacitance from  $V_{COMP}$  to GND. Therefore,  $C_7$  is optional. Use  $C_6 = 150pF$  and  $C_7 = \text{OPEN}$ .

$$C_3 = \frac{1}{\pi 100kHz \cdot 200k\Omega} = 16pF \quad (\text{EQ. 12})$$

Use  $C_3 = 10pF$ . Note that  $C_3$  may increase the loop bandwidth from previous estimated value. [Figure 45](#) shows the simulated voltage loop gain. It is shown that it has a  $120kHz$  loop bandwidth with a  $58^\circ$  phase margin and  $8dB$  gain margin. It may be more desirable to achieve an increased phase and gain margin. This can be accomplished by lowering  $R_6$  by 10% to 20%.

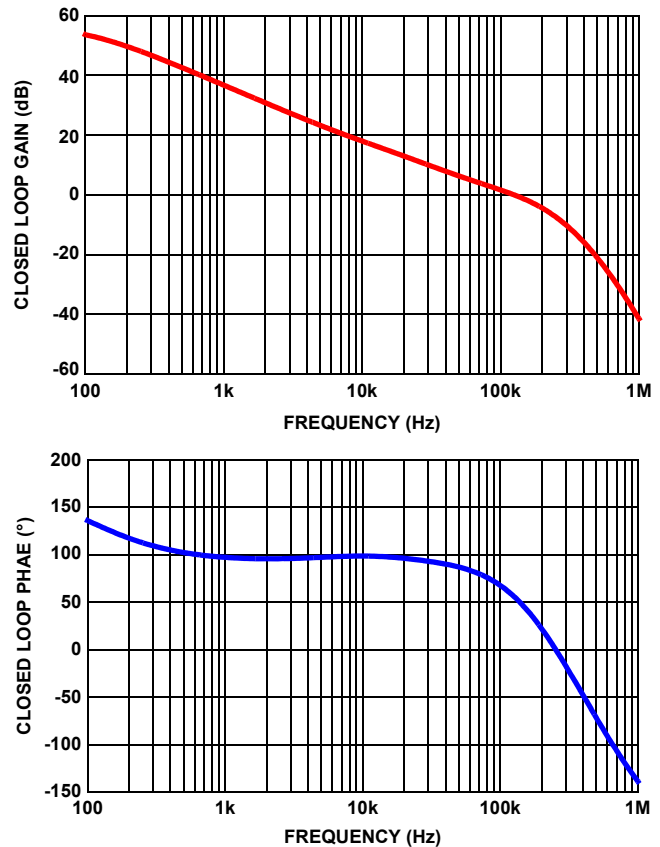


FIGURE 45. SIMULATED LOOP GAIN AND PHASE

## PCB Layout Recommendation

The PCB layout is a very important converter design step to make sure the designed converter works well. For the ISL78235R5668 the power loop is composed of the output inductor  $L_o$ , the output capacitor  $C_o$ , the PHASE pins, and the PGND pin. It is necessary to make the power loop as small as possible and the connecting traces among them should be direct, short, and wide. The switching node of the converter, the PHASE pins, and the traces connected to the node are very noisy, so keep the voltage feedback trace away from these noisy traces. The input capacitor should be placed as close as possible to the  $V_{IN}$  pin. The ground of the input and output capacitors should be connected as close as possible. The heat of the IC is mainly dissipated through the thermal pad. Maximizing the copper area connected to the thermal pad is preferable. In addition, a solid ground plane is helpful for better EMI performance. It is recommended to add at least five vias ground connection within the pad for the best thermal relief.

## Revision History

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

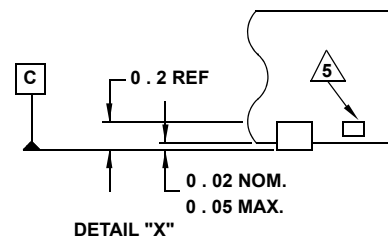
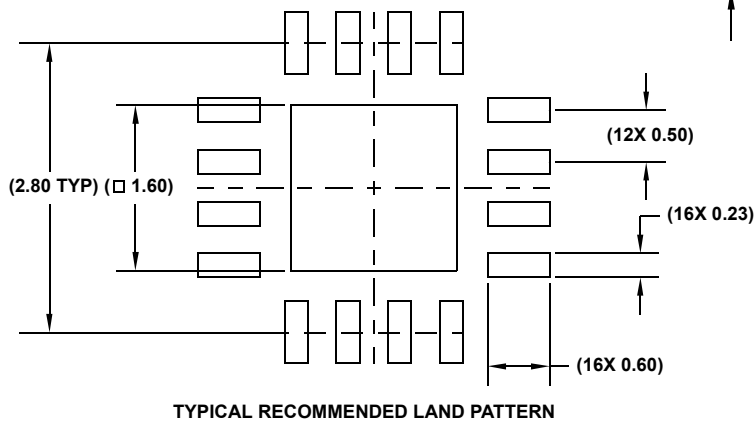
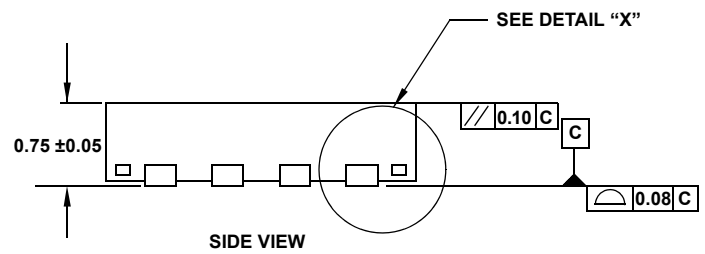
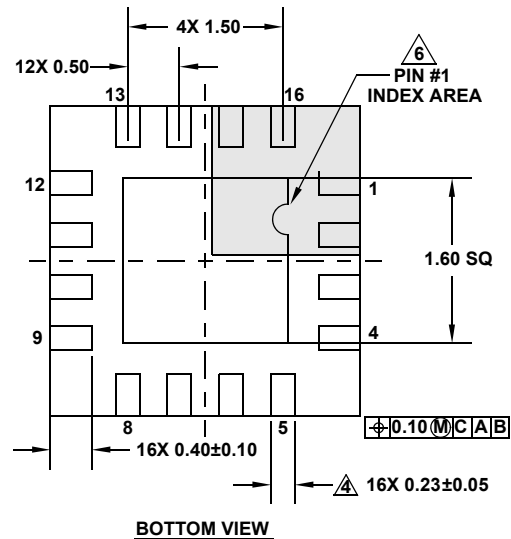
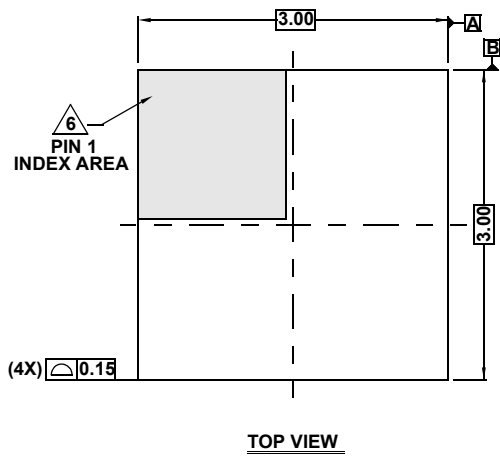
DATE	REVISION	CHANGE
Apr 19, 2018	FN8769.1	Updated Related Literature section on page 1. Page 7: Added Note 9: "EN should be held below the EN_VIL until $V_{IN}$ exceeds $V_{UVLO}$ rising." "Logic Input Low" parameter - added cross reference to Note 9. Added symbol name "EN_VIL" for "Logic Input Low" parameter. Added symbol name "EN_VIH" for "Logic Input High" parameter. Page 16: Added to end of Enable section: "EN should be held below the EN_VIL until $V_{IN}$ exceeds $V_{UVLO}$ rising." Removed About Intersil section. Added new disclaimer.
Jan 21, 2016	FN8769.1	Updated Ordering Information table on page 4 - added "TAPE AND REEL QUANTITY (UNITS)" column. Added Table 1 on page 4. Control Scheme page 14 last sentence of last paragraph Changed 1.6V to 2.5V.
Aug 11, 2015	FN8769.0	Initial Release

# Package Outline Drawing

## L16.3x3D

16 LEAD THIN QUAD FLAT NO-LEAD PLASTIC PACKAGE

Rev 0, 3/10

For the most recent package outline drawing, see [L16.3x3D](#).

### NOTES:

1. Dimensions are in millimeters.  
Dimensions in ( ) for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance: Decimal  $\pm 0.05$
4. Dimension applies to the metallized terminal and is measured between 0.15mm and 0.25mm from the terminal tip.
5. Tiebar shown (if present) is a non-functional feature.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
7. JEDEC reference drawing: MO-220 WEED.

## Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
  2. Renesas Electronics hereby expressly disclaims any warranties against liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
  3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
  4. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
  5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
  6. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
  7. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
  8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
  9. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
  10. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
  11. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
  12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.4.0-1 November 2017)



### SALES OFFICES

### Renesas Electronics Corporation

<http://www.renesas.com>

Refer to "<http://www.renesas.com/>" for the latest and detailed information.

#### **Renesas Electronics America Inc.**

1001 Murphy Ranch Road, Milpitas, CA 95035, U.S.A.  
Tel: +1-408-432-8888, Fax: +1-408-434-5351

#### **Renesas Electronics Canada Limited**

9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3  
Tel: +1-905-237-2004

#### **Renesas Electronics Europe Limited**

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.  
Tel: +44-1628-651-700, Fax: +44-1628-651-804

#### **Renesas Electronics Europe GmbH**

Arcadiastrasse 10, 40472 Düsseldorf, Germany  
Tel: +49-211-6503-0, Fax: +49-211-6503-1327

#### **Renesas Electronics (China) Co., Ltd.**

Room 1709 Quantum Plaza, No.27 ZhichunLu, Haidian District, Beijing, 100191 P. R. China  
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

#### **Renesas Electronics (Shanghai) Co., Ltd.**

Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, 200333 P. R. China  
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

#### **Renesas Electronics Hong Kong Limited**

Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong  
Tel: +852-2265-6688, Fax: +852 2886-9022

#### **Renesas Electronics Taiwan Co., Ltd.**

13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan  
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

#### **Renesas Electronics Singapore Pte. Ltd.**

80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949  
Tel: +65-6213-0200, Fax: +65-6213-0300

#### **Renesas Electronics Malaysia Sdn.Bhd.**

Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia  
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

#### **Renesas Electronics India Pvt. Ltd.**

No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India  
Tel: +91-80-67208700, Fax: +91-80-67208777

#### **Renesas Electronics Korea Co., Ltd.**

17F, KAMCO Yangjae Tower, 262, Gangnam-daero, Gangnam-gu, Seoul, 06265 Korea  
Tel: +82-2-558-3737, Fax: +82-2-558-5338